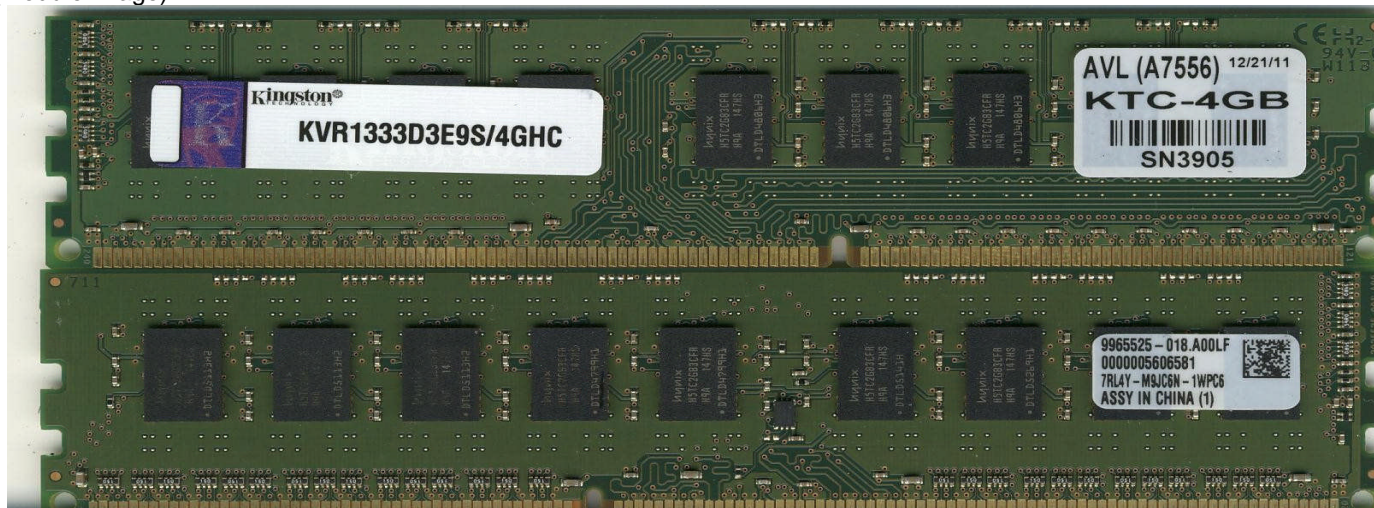



	<b>AVL Supermicro server platform Memory Module Qualification Test</b>		
	Intel X5650(WSM) x 2, Intel 5520 (Tylersburg), Rev C2	Test Results	Pass
	PN: KVR1333D3E9S/4GHC (4GB / UDIMM ECC / ECC ) On: X8DT3 Rev.2.00		

RP77D3x-106-KI-SQ-SMC-V1		Module Information		Rev 01/07/2011
AVL WorkOrder #	WC2600	AVL A#	7556	
Start Date	1/12/2012	End Date	1/18/2012	
Tested By	Van N			
Module Manufacturer	Kingston			
Module Part Number	KVR1333D3E9S/4GHC			
Module BOM Number	9965525-018.A00LF			
Module Capacity / Memory Type / ECC	4GB / UDIMM ECC/ ECC			
Module Configuration (Width, # of devices, # of Ranks)	512Mx72 /18 Devices / 2 Ranks			
Speed Tested (Data rate of Mbps, CL-tRP-tRCD)	DDR3-1333 /9-9-9			
DRAM Device Vendor	Hynix			
DRAM Device Part Number / Date code	H5TC2G83CFR-H9A		1147	
DRAM Die Revision / Process Technology ( nm )	C			
DRAM Device Config (Density / Width)	2Gbit / x8			
Thermal Sensor Device Vendor / Part Number / Revision				
Register Device Vendor / Part Number / Revision				

(Module image)



Platform System Information				
Motherboard Info (Model# & MB Revision & MB S/N & AVL S/N)	X8DT3	2.00	OM06S30241	SK4377
BIOS Revision / BIOS Date / MRC Rev.	2.0a	9/14/2010	2.11	
CPU / Speed	Intel X5650(WSM) x 2		2.66GHz	
Chipset info (Stepping)	Intel 5520 (Tylersburg), Rev C2			

	<b>AVL Supermicro server platform Memory Module Qualification Test</b>
	Intel X5650(WSM) x 2, Intel 5520 (Tylersburg), Rev C2 PN: KVR1333D3E9S/4GHC (4GB / UDIMM ECC / ECC ) On: X8DT3 Rev.2.00

<b>Test Results:</b>	<b>PASS</b>
<i>Comments:</i>	

### AVL Memory Module Qual Test Results Summary

Test # and name	Test Description	Specs	Test Results	Comments
<b>1. Latest BIOS Upgrade &amp; Configuration</b>	Download / Upgrade latest BIOS & record size and speed detection	Per test platform, DIMM & config spec	<b>Done</b>	Record memory size & speed at each test only
<b>2. SPD Check</b>	Memory module SPD content check for JEDEC compliance	JEDEC	<b>Pass</b>	Use proprietary tools
<b>3. Sisoftware Sandra Benchmark</b>	Run Windows based diags & utility software @50°C - DIMM max loading.	1 loop per config	<b>Done</b>	Full load per spec
<b>4. Passmark Burn-In</b>		6 Hour per config	<b>Pass</b>	Full load per spec
<b>5a. Stress Application Test</b>	Run Linux based diags & utility software @50°C - DIMM max loading.	8 Hour per config	<b>Pass</b>	Full load per spec
<b>5b. Stream Benchmark Test</b>		5 loop per config	<b>Done</b>	Full load per spec
<b>5c. Reset Cycle</b>		500 loop per config	<b>Pass</b>	Full load per spec
<b>6a. Functional Stress Test (Corner 1a)</b>	Run RST Premium @50°C - DIMM max loading.	8 Hour or 2+ Loops per config	<b>Pass</b>	Full load per spec
<b>6b. Functional Stress Test (Corner 1b)*</b>	Run RST Premium @55°C - DIMM loading depends on @speed configuration	8 Hour or 2+ Loops per config	<b>N/A</b>	Per platform memory speed configuration table if different (run @Max module speed)
<b>7. Functional Stress Test (Corner 2)</b>	Run RST Premium @0°C DIMM max loading	8 Hour or 2+ Loops per config	<b>N/A</b>	Full load per spec

Note: All test under IMC Vdd=Nom, Vref=Vddnom/2

\* Corner 1b test is not required if Corner 1A already covers max module speed.